



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Takayuki YAMAMOTO et al.

Appln. No. 09/735,892

Confirmation No.: 5759

Filed: December 14, 2000

For: REMOVABLE PRESSURE-SENSITIVE ADHESIVE SHEET

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. §§ 1.97 and 1.98

Commissioner for Patents
Washington, D.C. 20231

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56, Applicant hereby notifies the U.S. Patent and Trademark Office of the documents which are listed on the attached Form PTO-1449 and/or listed herein and which the Examiner may deem material to patentability of the claims of the above-identified application.

One copy of each of the listed documents is submitted herewith.

The present Information Disclosure Statement is being filed: (1) No later than three months from the application's filing date for an application other than a continued prosecution application (CPA) under §1.53(d); (2) Before the mailing date of the first Office Action on the merits (whichever is later); or (3) Before the mailing date of the first Office Action after filing a request for continued examination (RCE) under §1.114, and therefore, no Statement under 37 C.F.R. § 1.97(e) or fee under 37 C.F.R. § 1.17(p) is required.

RECEIVED
SEP 24 2001
Group Art Unit: 1772
Examiner: Not yet assigned

#3
I.D.S.
DR.

INFORMATION DISCLOSURE STATEMENT
U.S. Appln. No. 09/735,892

In compliance with the concise explanation requirement under 37 C.F.R. § 1.98(a)(3) for foreign language documents, Applicant submits the following explanations:

JP 8-330257:

This document has an object to provide a low stain pressure-sensitive adhesive sheet as a processing material for semiconductor, which is generally similar in purpose to the present invention. However, this document does not contain any disclosure to teach or suggest that the content of low molecular weight components is limited to 10 wt% or lower as in the present invention.

JP 9-7981:

This document has an object to provide a low stain pressure-sensitive adhesive sheet as a processing material for semiconductor, which is generally similar in purpose to the present invention. However, this document does not contain any disclosure to teach or suggest that the content of low molecular weight components is limited to 10 wt% or lower as in the present invention.

JP 9-36069:

This document has an object to provide a low stain pressure-sensitive adhesive sheet as a processing material for semiconductor, which is generally similar in purpose to the present invention. However, this document does not contain any disclosure to teach or suggest that the content of low molecular weight components is limited to 10 wt% or lower as in the present invention.

INFORMATION DISCLOSURE STATEMENT
U.S. Appln. No. 09/735,892

JP 9-71757:

This document has an object to provide a low stain pressure-sensitive adhesive sheet as a processing material for semiconductor, which is generally similar in purpose to the present invention. However, this document does not contain any disclosure to teach or suggest that the content of low molecular weight components is limited to 10 wt% or lower as in the present invention.

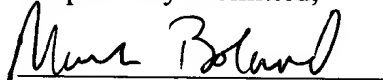
JP 9-272846:

This document has an object to provide a low stain pressure-sensitive adhesive sheet as a processing material for semiconductor, which is generally similar in purpose to the present invention. However, this document does not contain any disclosure to teach or suggest that the content of low molecular weight components is limited to 10 wt% or lower as in the present invention.

The submission of the listed documents is not intended as an admission that any such document constitutes prior art against the claims of the present application. Applicant does not waive any right to take any action that would be appropriate to antedate or otherwise remove any listed document as a competent reference against the claims of the present application.

SUGHRUE, MION, ZINN,
MACPEAK & SEAS, PLLC
2100 Pennsylvania Avenue, N.W.
Washington, D.C. 20037-3213
Telephone: (202) 293-7060
Facsimile: (202) 293-7860
Date: September 20, 2001

Respectfully submitted,



Mark Boland
Registration No. 32,197